

## Roll-to-Roll Processing for Solution Processed OLED Devices

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10,000 €/m²
Rigid glass
40-60 % material loss
Vacuum/litho processes
Rare materials
Glass encapsulation

Flexible substrates
<5% material loss

Direct printing processes

Mainstream materials

Thin-film encapsulation

© Holst Centre OLED Processing 4

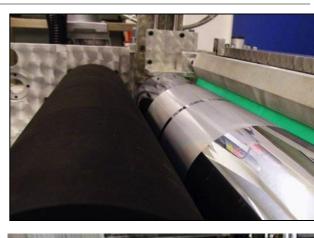
# R2R Printing & Coating technology Why?

# Printing/casting preferred over lithographic patterning

- easier for large scale processing
- fine features/patterning without complicated masks
- higher materials utilisation → lower cost

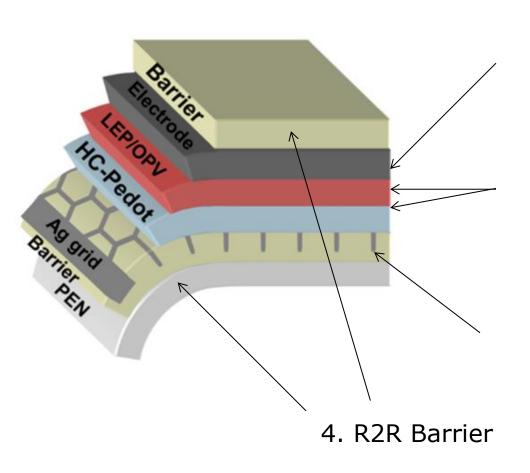
#### **Topics:**

- √ S2S up scalable to R2R
- Multilayer coating
- ✓ Patterning & alignment
- ✓ Prevention of contamination yield control





# **Summary: Schematic of R2R solution processed OLED** (ITO free)



3. Shunting cathode OLEDs by IJP

2. Large area coating

1. Printing and sintering of silver grids (anode)

#### 1. Printing & Sintering

Printing silver: Ink jet – Screen printing





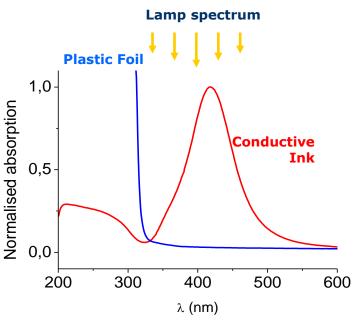
- Baseline Process: Thermal Sintering in furnace at high temperatures (30 min./>150 °C)
  - Limited to T<sub>g</sub> of polymer foils
  - Slow and inefficient process
  - In R2R line with 6 m/min a furnace of 60 m needed
- Photonic Flash Sintering

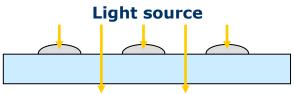
#### **Photonic sintering principle**

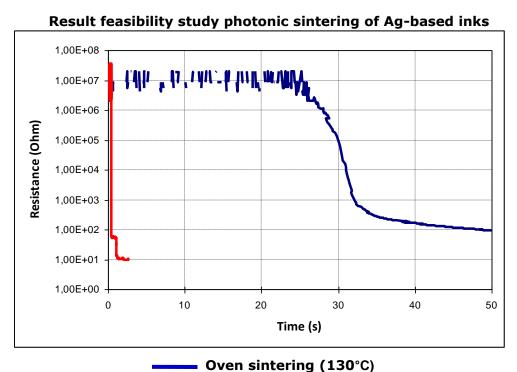
The principle of photonic sintering is the selective heating of the ink

Lamps are chosen such that the light is mainly absorbed in the printed structures, not

substrate







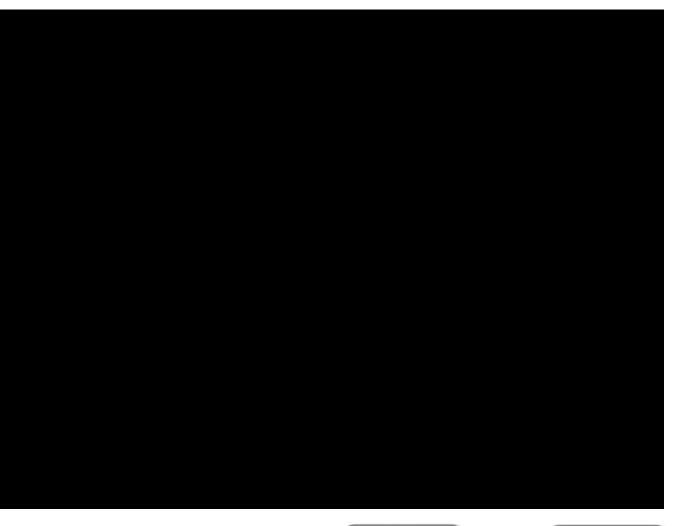
#### **Achievements:**

- Sintering time reduced from minutes to few seconds!

**Optimized Flash sintering** 









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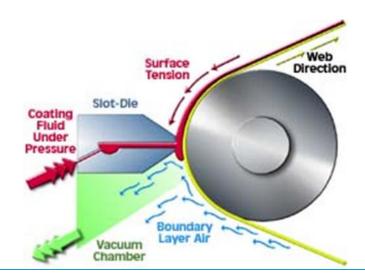
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Extended to 5 print heads

#### 2. Large area coating (using solution processing)

#### **Holst Centre's Approaches:**

- **0) Spin coating:** simple, no patterning
- 1) Ink-jet printing: non-contact, patterning is easy
  - Homogeneity over large areas needs to be investigated
- 2) Slot-die coating: non-contact, large area blanket coating
  - **Pattering:** via laser ablation or selective wetting/dewetting or stripe coating and **intermittant coating**



## **Slot die casting at Holst**



- -Pattering !!!
- -R2R atmosphere control
- -Yield

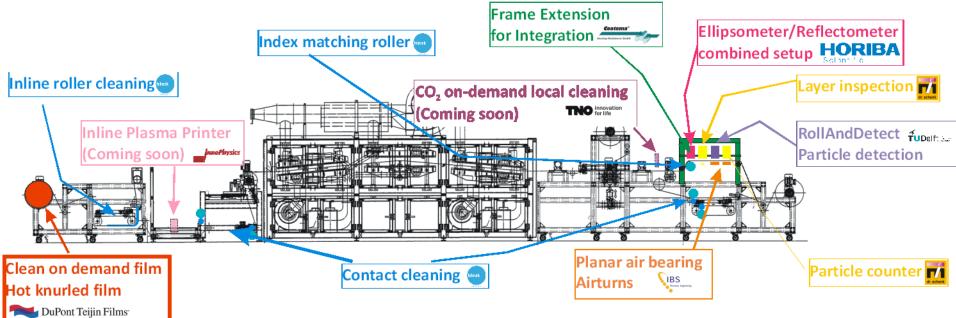




#### **Integration at Holst Centre**



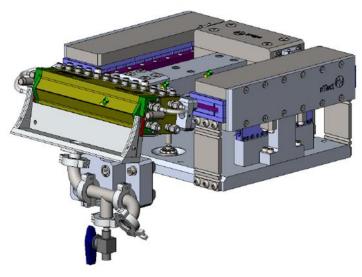




## Patterning slot die



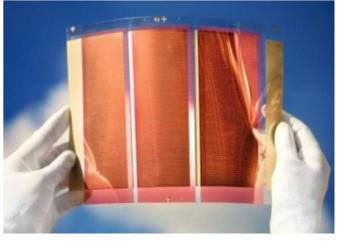
Intermittent coating with slot-die





#### Stripe Coating



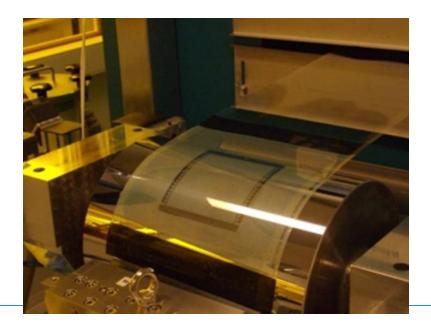




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# OLEDs: Large area slot die coated flexible demonstrators

- Slot-die coated layers of 100 30 nm with thickness variation only ± 2 nm
- Sequential coating of up to 3 organic layers on plastic and metal foil proven





## **Roll-to-roll multilayer coating of OLEDs**

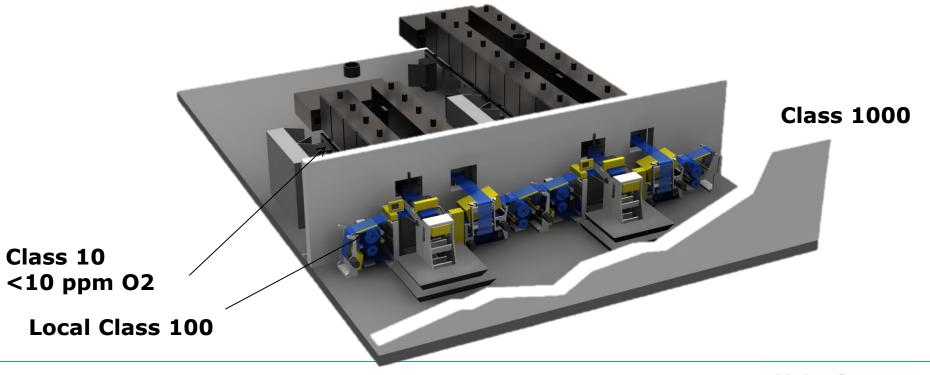
Roll-to-roll multilayer solution coated OLEDs on flexible metal foil

Homogeneity 60% @ 1000 cd/m² mostly limited by transparent electrode conductivity

8 cm x 8 cm devices with performance not far from smaller sheet-to-sheet processed OLEDs

# Holst Centre multicoat (2 x slot coating) pilot production line

- Unique concept where web is never touched on topside essential for Oled production.
- Concept makes very efficient use of cleanroom space.
- Slot die coating in controlled atmosphere (all coating and drying in Nitrogen environment if needed).
- Closed furnace (class 10 + < 10 ppm O<sub>2</sub>/H<sub>2</sub>O)



#### **Multicoat R2R line**

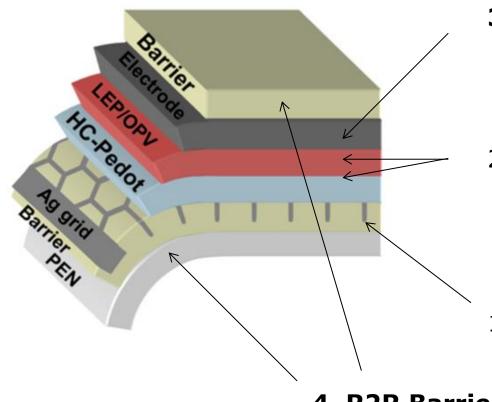








## **Summary: Schematic of R2R solution processed OLED** (ITO free)



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2. Large area coating

1. Printing and sintering of silver grids (anode)

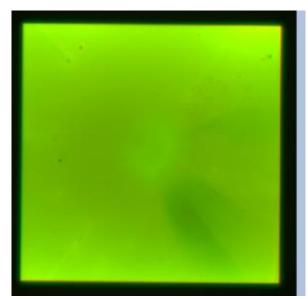
4. R2R Barrier

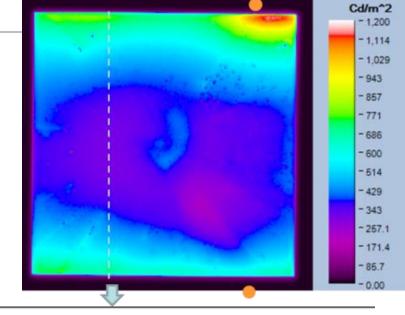
# 3. IJP grid to improve transparent electrode conductivity

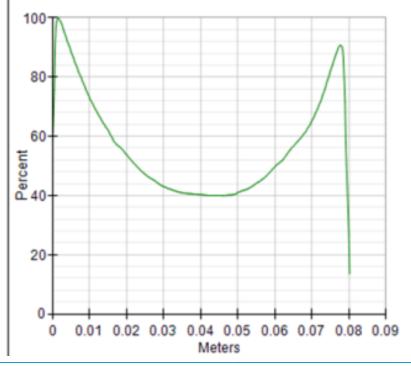
Device size 80 x 80 mm2

Without shunting lines:

Inhomogeneous due to limited conductivity of transparent cathode

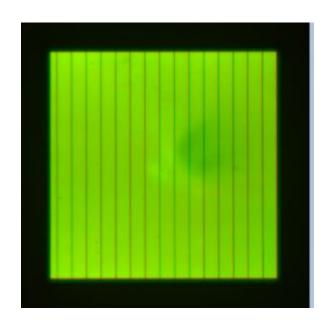


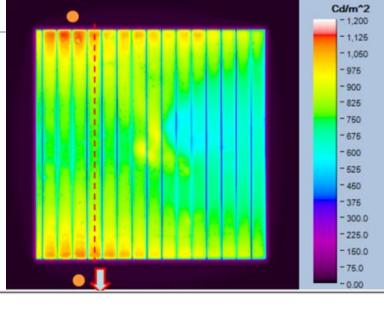


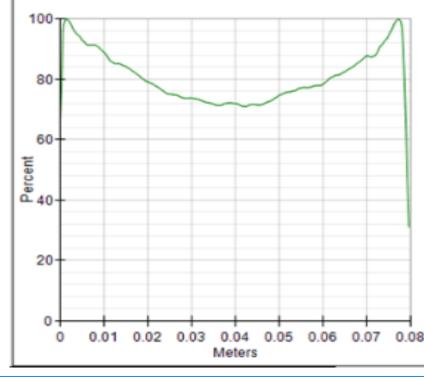


#### With ink jet printed shunting lines:

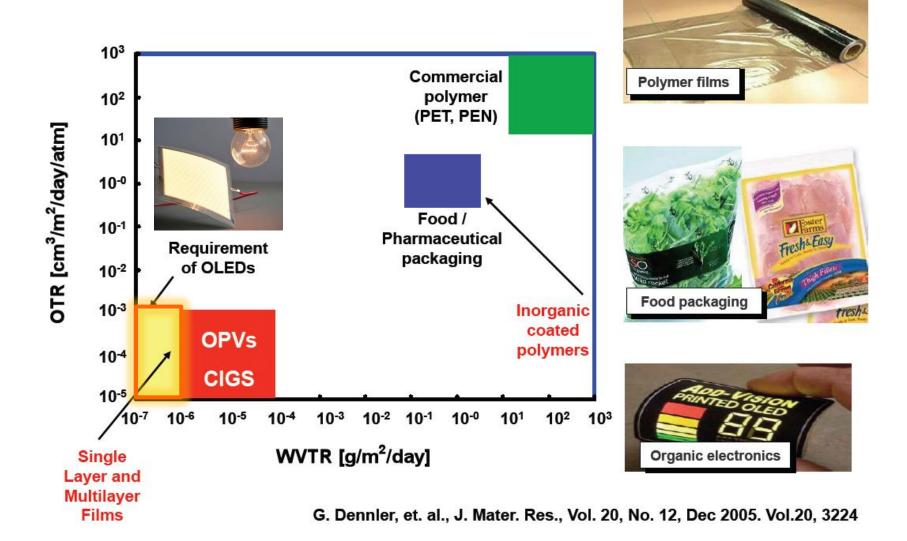
Less inhomogeneous due to shunt lines







#### 4. Barrier Requirements Organic Electronics

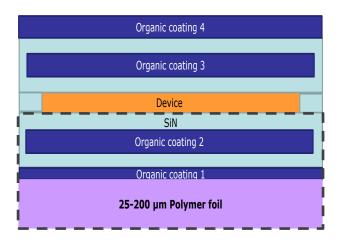


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#### S2S Thin Film Barrier Technology @ Holst Centre

#### Holst Centre barrier fundamentals:

- Multilayer thin film barrier
  - PECVD SiN organic coating PECVD SiN
- Inorganic layer (PECVD SiN)
  - real barrier with WVTR < 10<sup>-6</sup> g/m<sup>2</sup>/day
  - full coverage of cathode
- Organic layer
  - decouple pinholes
- Only 3 layers to keep costs low
- Transparent:
  - suitable for top-emission or bottomemission OI FDs
- Validation done on real OLEDs against product spec:
  - Black spot analysis in accelerated shelf lifetime test (60°C/90% RH)



#### 4 R2R barrier film

- WVTR of the single SiN sampled over 350m length at 60°C and 90%RH for 20 days : Overall WVTR =  $(5\pm1)\cdot10^{-5}$  g/m<sup>2</sup>day
- 450 m/day
- Full barrier stack R2R processed (OCP-SiN-OCP-SiN)

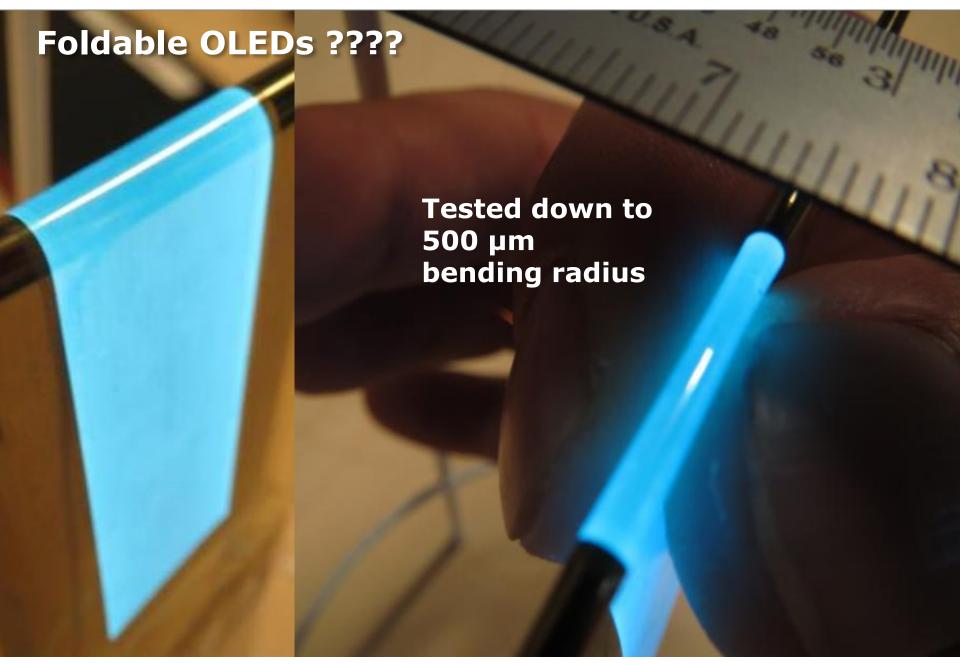




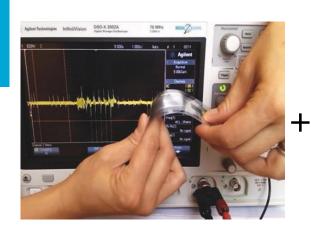






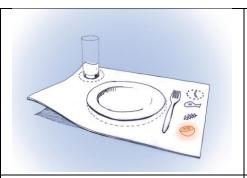


# Integration Light Touch Matters









Smart placemat to improve people's diet



Wristband for reminders and feedback



Force-sensitive grip for expressing anxiety



Intuitive interface for Emergency defibrilator



#### **Conclusion**

## Lighting based on printing/ coating technologies

The research leading to these results has received funding from the European Union Seventh Framework Programme (FP7/2007-2013) under grant agreement no 281027 and 310311



